

EVVOSEMI[®]

THINK CHANGE DO



ESD



TVS



MOS



LDO



Diode



Sensor



DC-DC

Product Specification

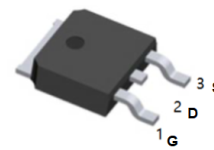
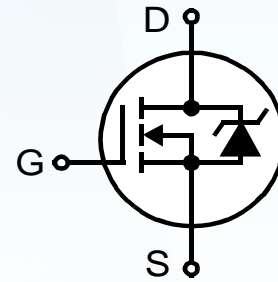
▶ Domestic	Part Number	FDD8896
▶ Overseas	Part Number	FDD8896
▶ Equivalent	Part Number	FDD8896

EV is the abbreviation of name EVVO

30V N-Channel MOSFET

Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(ON)}$ and fast switching speed.



TO-252(DPAK) top view

Features

- V_{DS} (V) = 30V
- I_D = 35A (V_{GS} = 10V)
- $R_{DS(ON)}$ = 5.7m Ω (V_{GS} = 10V)
- $R_{DS(ON)}$ = 6.8m Ω (V_{GS} = 4.5V)

MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V_{DSS}	Drain to Source Voltage	30	V
V_{GS}	Gate to Source Voltage	± 20	V
I_D	Drain Current		
	Continuous ($T_C = 25^\circ\text{C}$, $V_{GS} = 10\text{V}$) (Note 1)	94	A
	Continuous ($T_C = 25^\circ\text{C}$, $V_{GS} = 4.5\text{V}$) (Note 1)	85	A
	Continuous ($T_{amb} = 25^\circ\text{C}$, $V_{GS} = 10\text{V}$, with $R_{\theta JA} = 52^\circ\text{C/W}$)	17	A
	Pulsed	Figure 4	A
E_{AS}	Single Pulse Avalanche Energy (Note 2)	168	mJ
P_D	Power dissipation	80	W
	Derate above 25°C	0.53	W/ $^\circ\text{C}$
T_J, T_{STG}	Operating and Storage Temperature	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case TO-252	1.88	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-252	100	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance Junction to Ambient TO-252, 1in ² copper pad area	52	$^\circ\text{C/W}$

30V N-Channel MOSFET

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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Off Characteristics

B_{VDSS}	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 24\text{V}$ $V_{GS} = 0\text{V}$	-	-	1	μA
		$T_C = 150^\circ\text{C}$	-	-	250	
I_{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(TH)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.2	-	2.5	V
$r_{DS(ON)}$	Drain to Source On Resistance	$I_D = 35\text{A}, V_{GS} = 10\text{V}$	-	47	57	$\text{m}\Omega$
		$I_D = 35\text{A}, V_{GS} = 4.5\text{V}$	-	57	68	
		$I_D = 35\text{A}, V_{GS} = 10\text{V},$ $T_J = 175^\circ\text{C}$	-	75	92	

Dynamic Characteristics

C_{ISS}	Input Capacitance	$V_{DS} = 15\text{V}, V_{GS} = 0\text{V},$ $f = 1\text{MHz}$	-	2525	-	pF	
C_{OSS}	Output Capacitance		-	490	-	pF	
C_{RSS}	Reverse Transfer Capacitance		-	300	-	pF	
R_G	Gate Resistance	$V_{GS} = 0.5\text{V}, f = 1\text{MHz}$	-	2.1	-	Ω	
$Q_g(TOT)$	Total Gate Charge at 10V	$V_{GS} = 0\text{V to } 10\text{V}$	$V_{DD} = 15\text{V}$ $I_D = 35\text{A}$ $I_g = 1.0\text{mA}$	-	46	60	nC
$Q_g(5)$	Total Gate Charge at 5V	$V_{GS} = 0\text{V to } 5\text{V}$		-	24	32	nC
$Q_g(TH)$	Threshold Gate Charge	$V_{GS} = 0\text{V to } 1\text{V}$		-	2.3	3.0	nC
Q_{gs}	Gate to Source Gate Charge			-	6.9	-	nC
Q_{gs2}	Gate Charge Threshold to Plateau			-	4.6	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	9.8	-	nC

Switching Characteristics ($V_{GS} = 10\text{V}$)

t_{ON}	Turn-On Time	$V_{DD} = 15\text{V}, I_D = 35\text{A}$ $V_{GS} = 10\text{V}, R_{GS} = 6.2\Omega$	-	-	171	ns
$t_{d(ON)}$	Turn-On Delay Time		-	9	-	ns
t_r	Rise Time		-	106	-	ns
$t_{d(OFF)}$	Turn-Off Delay Time		-	53	-	ns
t_f	Fall Time		-	41	-	ns
t_{OFF}	Turn-Off Time		-	-	143	ns

Drain-Source Diode Characteristics

V_{SD}	Source to Drain Diode Voltage	$I_{SD} = 35\text{A}$	-	-	1.25	V
		$I_{SD} = 15\text{A}$	-	-	1.0	V
t_{rr}	Reverse Recovery Time	$I_{SD} = 35\text{A}, dl_{SP}/dt = 100\text{A}/\mu\text{s}$	-	-	27	ns
Q_{RR}	Reverse Recovered Charge	$I_{SD} = 35\text{A}, dl_{SP}/dt = 100\text{A}/\mu\text{s}$	-	-	12	nC

Notes:

- 1: Package current limitation is 35A.
- 2: Starting $T_J = 25^\circ\text{C}, L = 0.43\text{mH}, I_{AS} = 28\text{A}, V_{DD} = 27\text{V}, V_{GS} = 10\text{V}.$

30V N-Channel MOSFET

Typical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

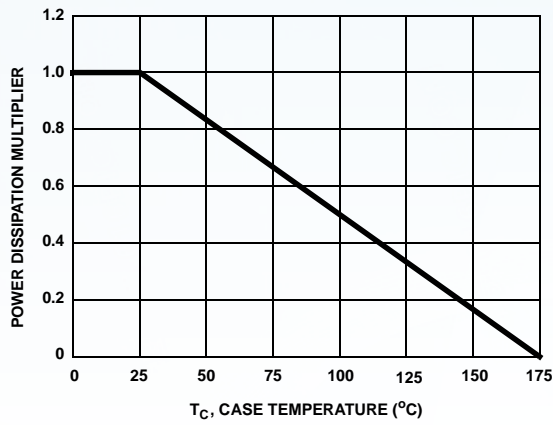


Figure 1. Normalized Power Dissipation vs Case Temperature

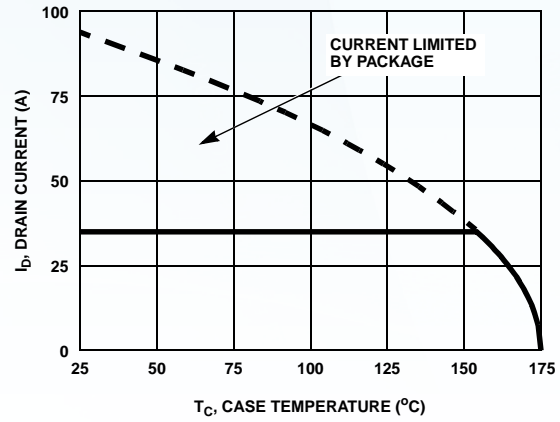


Figure 2. Maximum Continuous Drain Current vs Case Temperature

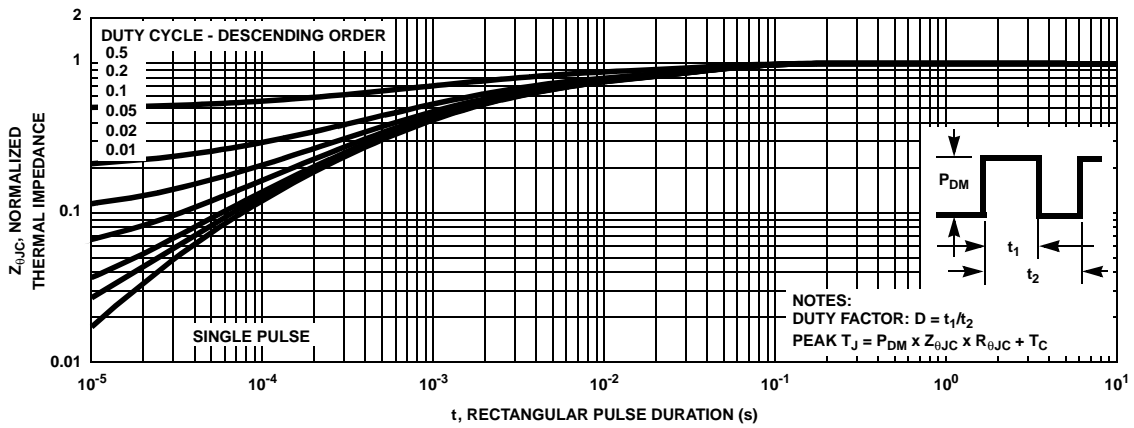


Figure 3. Normalized Maximum Transient Thermal Impedance

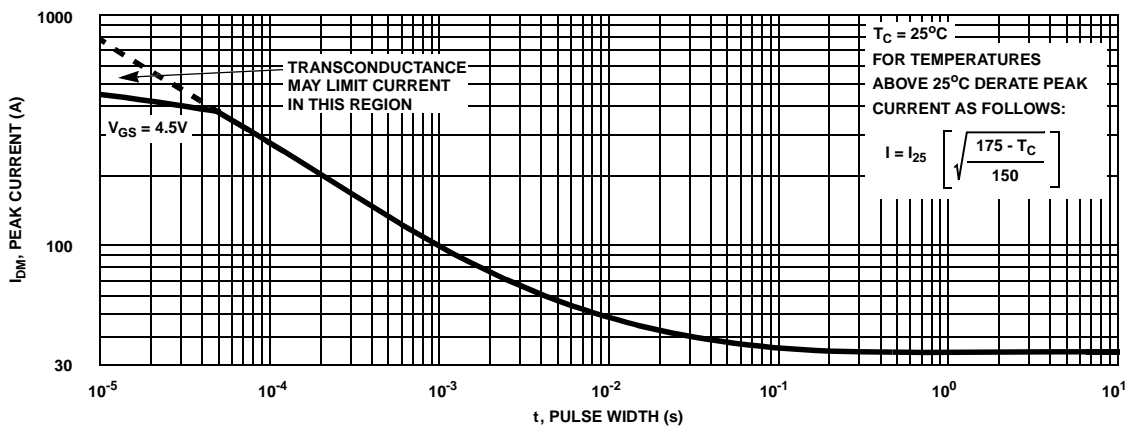


Figure 4. Peak Current Capability

30V N-Channel MOSFET

Typical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

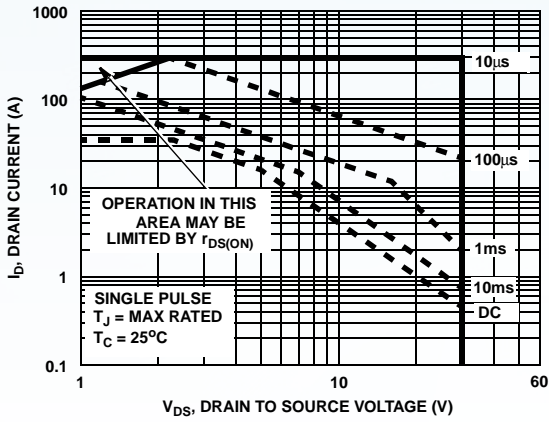
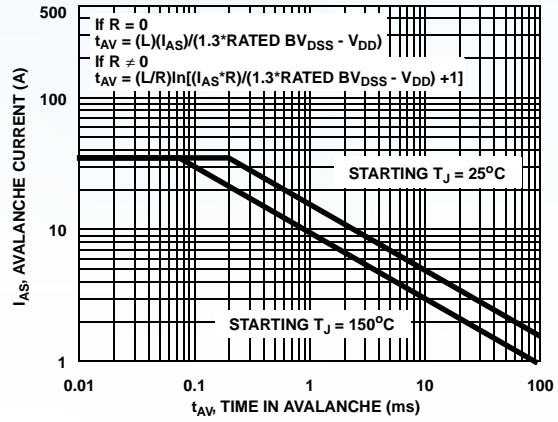


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515
Figure 6. Unclamped Inductive Switching Capability

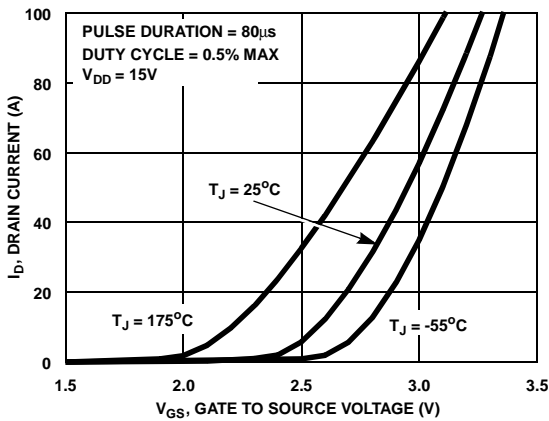


Figure 7. Transfer Characteristics

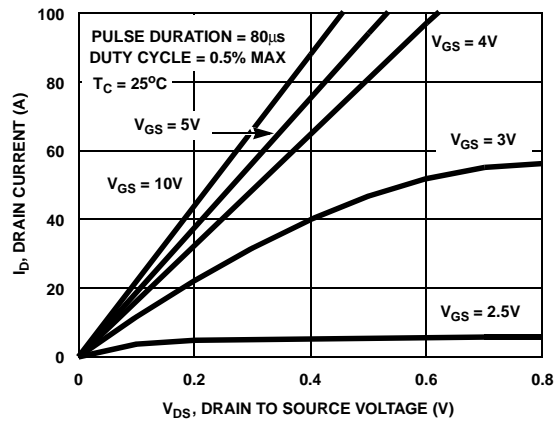


Figure 8. Saturation Characteristics

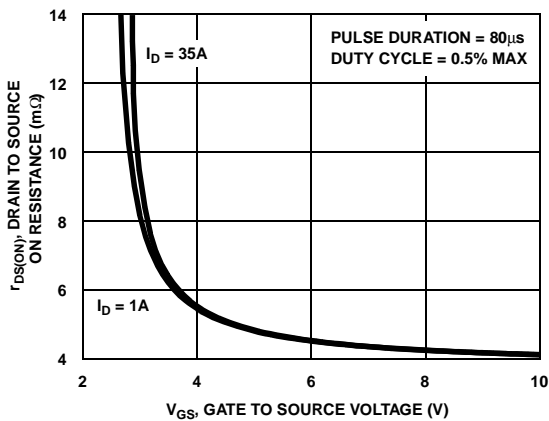


Figure 9. Drain to Source On Resistance vs Gate Voltage and Drain Current

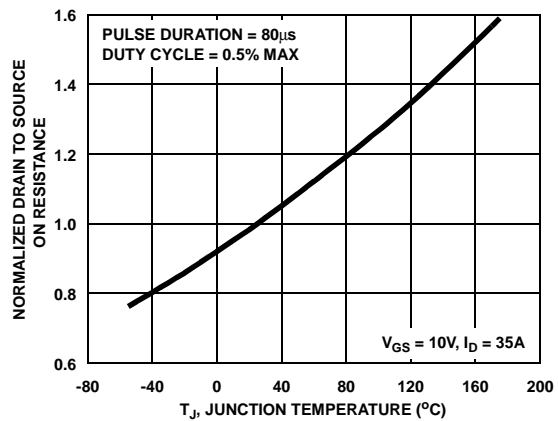


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

30V N-Channel MOSFET

Typical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

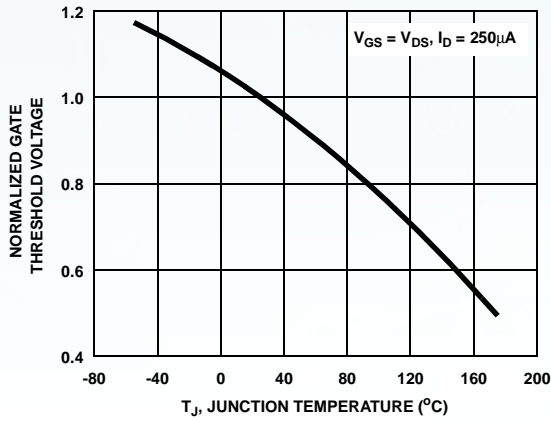


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

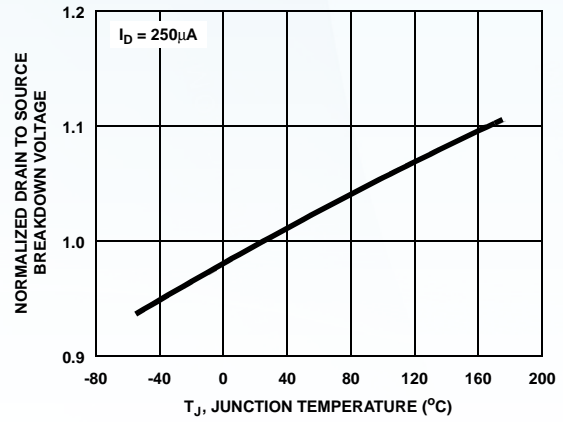


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

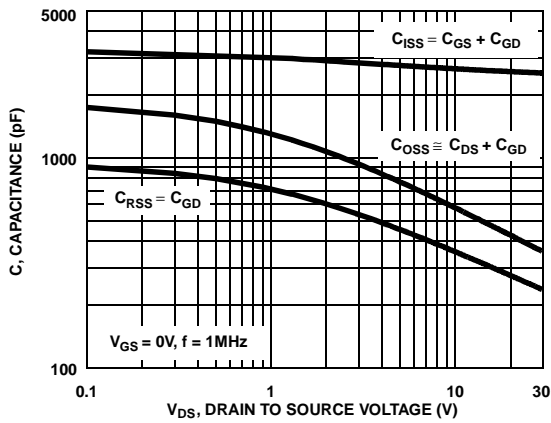


Figure 13. Capacitance vs Drain to Source Voltage

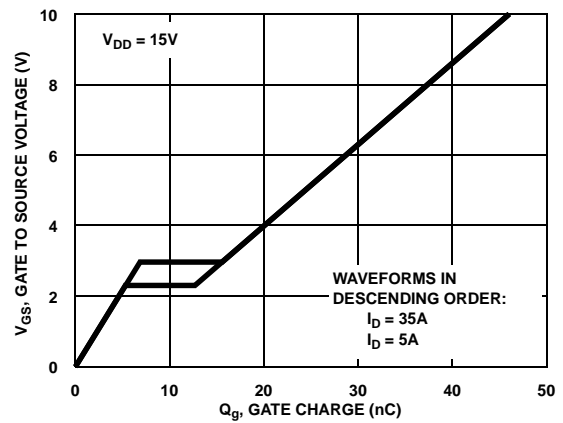


Figure 14. Gate Charge Waveforms for Constant Gate Current

30V N-Channel MOSFET

Test Circuits and Waveforms

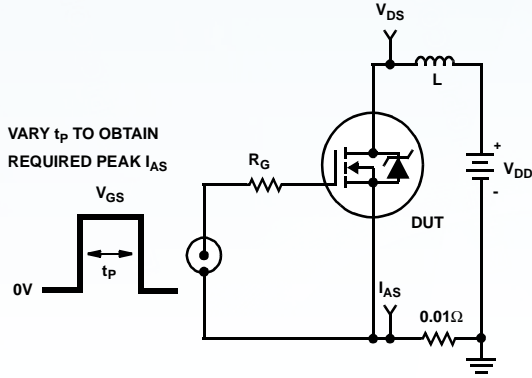


Figure 15. Unclamped Energy Test Circuit

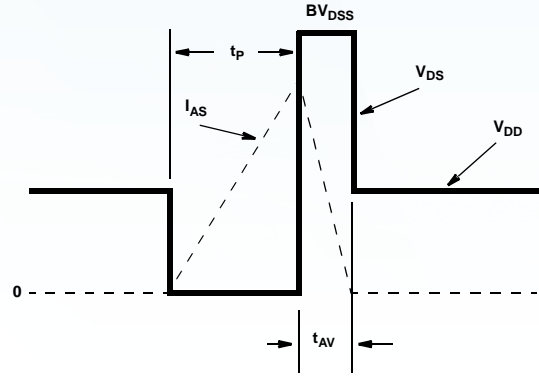


Figure 16. Unclamped Energy Waveforms

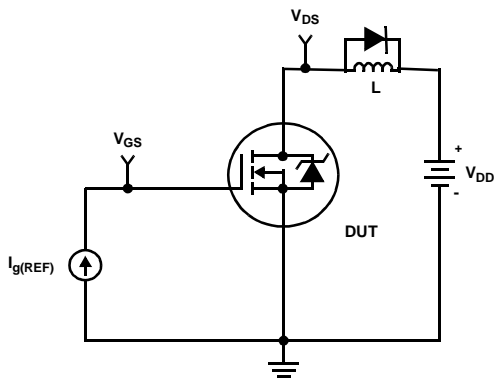


Figure 17. Gate Charge Test Circuit

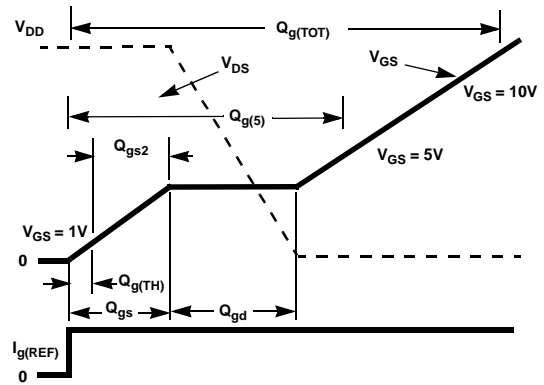


Figure 18. Gate Charge Waveforms

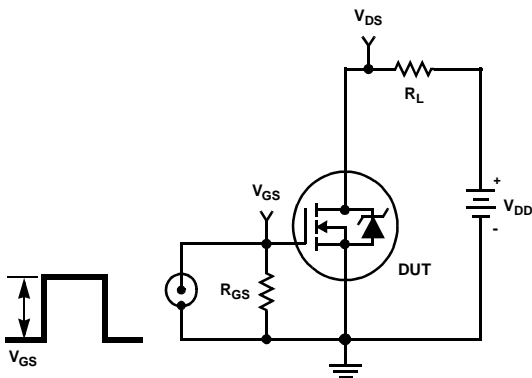


Figure 19. Switching Time Test Circuit

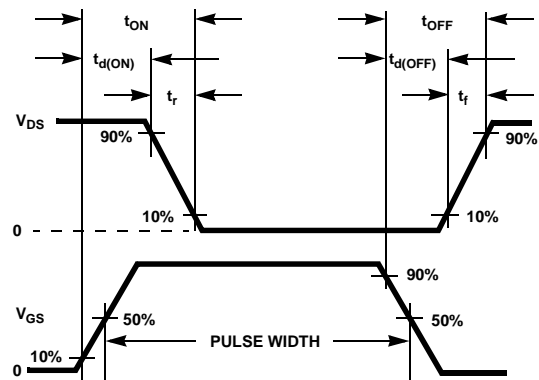
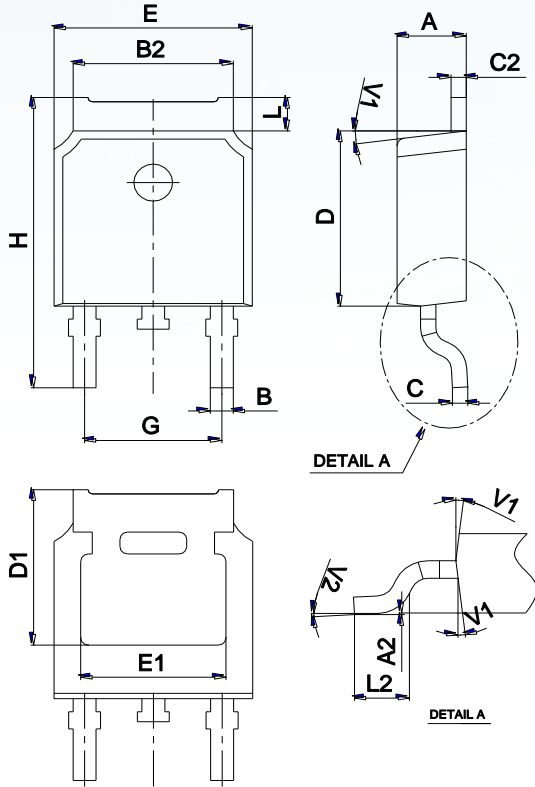


Figure 20. Switching Time Waveforms

30V N-Channel MOSFET

Package Mechanical Data TO-252



Ref.	Dimensions					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	2.10		2.50	0.083		0.098
A2	0		0.10	0		0.004
B	0.66		0.86	0.026		0.034
B2	5.18		5.48	0.202		0.216
C	0.40		0.60	0.016		0.024
C2	0.44		0.58	0.017		0.023
D	5.90		6.30	0.232		0.248
D1	5.30REF			0.209REF		
E	6.40		6.80	0.252		0.268
E1	4.63			0.182		
G	4.47		4.67	0.176		0.184
H	9.50		10.70	0.374		0.421
L	1.09		1.21	0.043		0.048
L2	1.35		1.65	0.053		0.065
V1		7°			7°	
V2	0°		6°	0°		6°

Ordering information

Order code	Package	Baseqty	Delivery mode
FDD8896	TO-252	2500	Tape and reel

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